

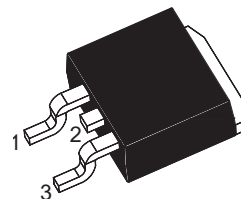
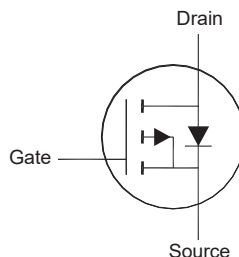
P-Channel Enhancement Mode MOSFET

Features

- High speed switch
- Advanced trench cell design
- Halogen and Antimony Free(HAF), RoHS compliant

Applications

- Portable appliances
- Battery management



1.Gate 2.Drain 3.Source
TO-263 Plastic Package

Key Parameters

Parameter	Value	Unit
$-BV_{DS}$	60	V
$R_{DS(ON)}$ Max	24 @ $-V_{GS} = 10\text{ V}$	mΩ
	33 @ $-V_{GS} = 4.5\text{ V}$	
$-V_{GS(th)}$ typ	1.8	V
Q_g typ	72 @ $-V_{GS} = 10\text{ V}$	nC

Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$-V_{DS}$	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current	$-I_D$	39	A
		24	
Peak Drain Current ¹⁾	$-I_{DM}$	140	A
Avalanche Current	$-I_{AS}$	40.6	A
Avalanche Energy ²⁾	E_{AS}	82.4	mJ
Power Dissipation	P_D	52	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	2.4	$^\circ\text{C/W}$
Thermal Resistance from Junction to Ambient ³⁾	$R_{\theta JA}$	45	$^\circ\text{C/W}$

¹⁾ Pulse Test: Pulse Width $\leq 100\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$, Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ\text{C}$.

²⁾ Limited by $T_{J(MAX)}$, starting $T_J = 25^\circ\text{C}$, $L = 0.1\text{ mH}$, $R_g = 25\text{ }\Omega$, $-I_{AS} = 40.6\text{ A}$, $V_{GS} = 10\text{ V}$.

³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at $-I_D = 250\ \mu\text{A}$	$-BV_{DS}$	60	-	-	V
Drain-Source On-State Current at $-V_{DS} = 48\ \text{V}$	$-I_{DSS}$	-	-	1	μA
Gate-Source Leakage Current at $V_{GS} = \pm 16\ \text{V}$	I_{GSS}	-	-	± 100	nA
Gate-Source Threshold Voltage at $V_{DS} = V_{GS}$, $-I_D = 250\ \mu\text{A}$	$-V_{GS(th)}$	1.3	-	2.5	V
Drain-Source On-State Resistance at $-V_{GS} = 10\ \text{V}$, $-I_D = 18\ \text{A}$ at $-V_{GS} = 4.5\ \text{V}$, $-I_D = 15\ \text{A}$	$R_{DS(ON)}$	- -	18 -	24 33	m Ω
DYNAMIC PARAMETERS					
Forward Transconductance at $-V_{DS} = 5\ \text{V}$, $-I_D = 10\ \text{A}$	g_{fs}	-	30	-	S
Gate resistance at $V_{DS} = 0\ \text{V}$, $V_{GS} = 0\ \text{V}$, $f = 1\ \text{MHz}$	R_g	-	5	-	Ω
Input Capacitance at $V_{GS} = 0\ \text{V}$, $-V_{DS} = 30\ \text{V}$, $f = 1\ \text{MHz}$	C_{iss}	-	4631	-	pF
Output Capacitance at $V_{GS} = 0\ \text{V}$, $-V_{DS} = 30\ \text{V}$, $f = 1\ \text{MHz}$	C_{oss}	-	186	-	pF
Reverse Transfer Capacitance at $V_{GS} = 0\ \text{V}$, $-V_{DS} = 30\ \text{V}$, $f = 1\ \text{MHz}$	C_{rss}	-	98	-	pF
Total Gate Charge at $-V_{GS} = 10\ \text{V}$, $-V_{DS} = 30\ \text{V}$, $-I_D = 18\ \text{A}$ at $-V_{GS} = 4.5\ \text{V}$, $-V_{DS} = 30\ \text{V}$, $-I_D = 18\ \text{A}$	Q_g	- -	72 33	- -	nC
Gate-Source Charge at $-V_{GS} = 10\ \text{V}$, $-V_{DS} = 30\ \text{V}$, $-I_D = 18\ \text{A}$	Q_{gs}	-	17	-	nC
Gate-Drain Charge at $-V_{GS} = 10\ \text{V}$, $-V_{DS} = 30\ \text{V}$, $-I_D = 18\ \text{A}$	Q_{gd}	-	11	-	nC
Turn-On Delay Time at $-V_{GS} = 10\ \text{V}$, $-V_{DD} = 30\ \text{V}$, $-I_D = 18\ \text{A}$, $R_G = 3.3\ \Omega$	$t_{d(on)}$	-	23	-	ns
Turn-On Rise Time at $-V_{GS} = 10\ \text{V}$, $-V_{DD} = 30\ \text{V}$, $-I_D = 18\ \text{A}$, $R_G = 3.3\ \Omega$	t_r	-	84	-	ns
Turn-Off Delay Time at $-V_{GS} = 10\ \text{V}$, $-V_{DD} = 30\ \text{V}$, $-I_D = 18\ \text{A}$, $R_G = 3.3\ \Omega$	$t_{d(off)}$	-	52	-	ns
Turn-Off Fall Time at $-V_{GS} = 10\ \text{V}$, $-V_{DD} = 30\ \text{V}$, $-I_D = 18\ \text{A}$, $R_G = 3.3\ \Omega$	t_f	-	23	-	ns
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at $-I_S = 1\ \text{A}$, $V_{GS} = 0\ \text{V}$	$-V_{SD}$	-	-	1.3	V
Body-Diode Continuous Current	$-I_S$	-	-	39	A
Body-Diode Continuous Current, Pulsed	$-I_{SM}$	-	-	140	A
Body Diode Reverse Recovery Time at $-I_S = 18\ \text{A}$, $di/dt = 100\ \text{A} / \mu\text{s}$	t_{rr}	-	28	-	ns
Body Diode Reverse Recovery Charge at $-I_S = 18\ \text{A}$, $di/dt = 100\ \text{A} / \mu\text{s}$	Q_{rr}	-	40	-	nC

Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

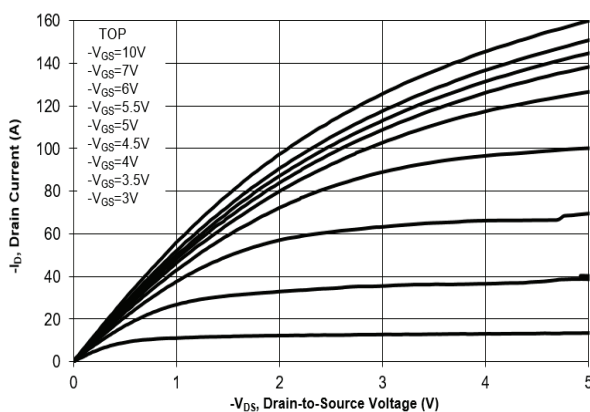


Fig. 2 Typical Transfer Characteristics

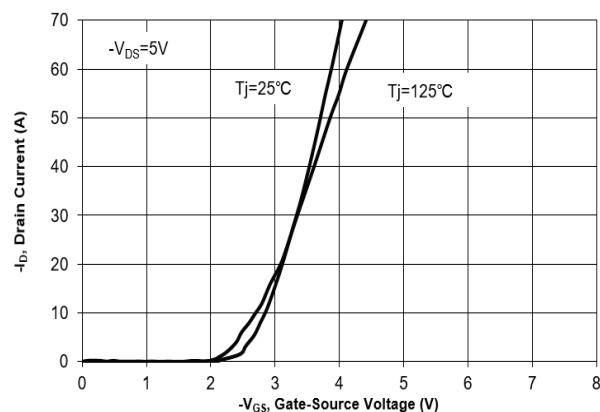


Fig. 3 on-Resistance vs. Drain Current

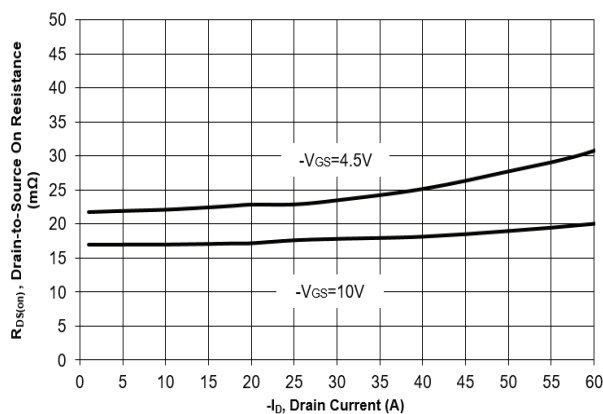


Fig. 4 on-Resistance vs. Gate to Source Voltage

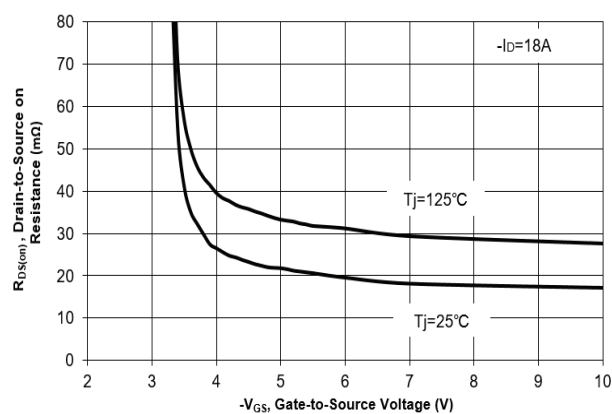


Fig. 5 on-Resistance vs. T_J

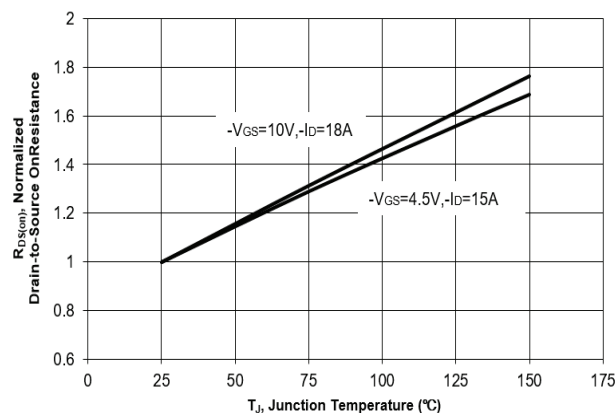
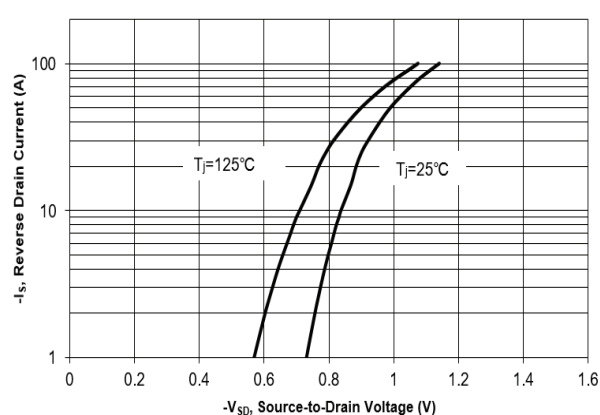


Fig. 6 Typical Body-Diode Forward Characteristics



Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

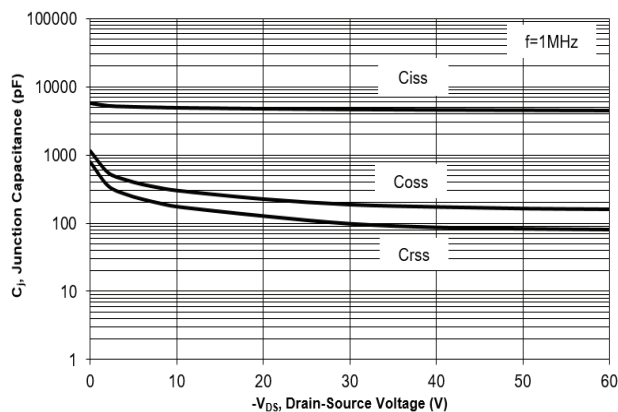


Fig. 8 Drain-Source Leakage Current vs. T_J

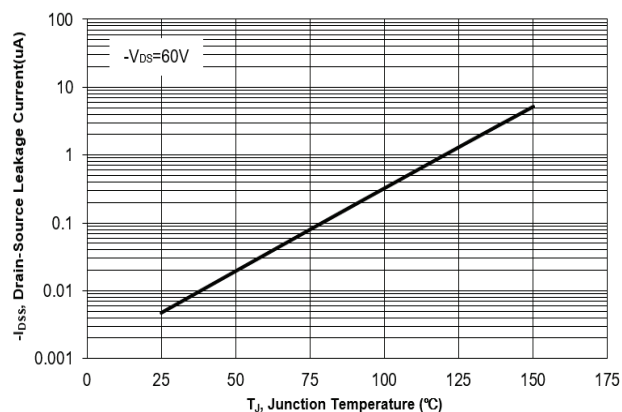


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

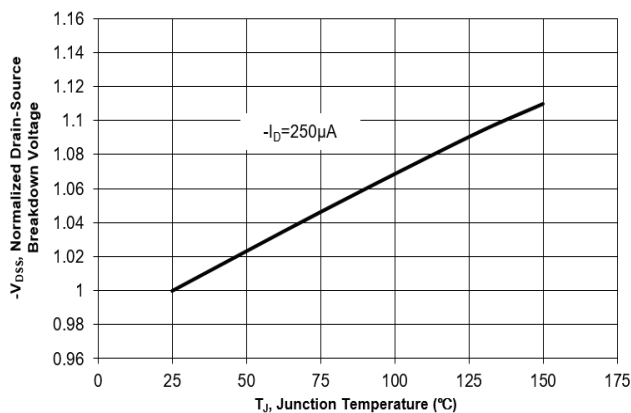


Fig. 10 Gate Threshold Variation vs. T_J

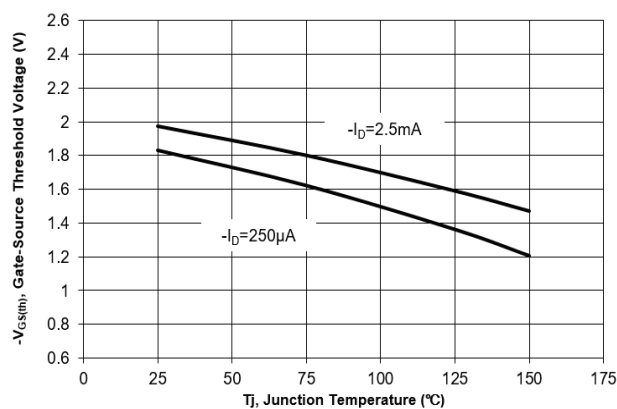


Fig. 11 Gate Charge

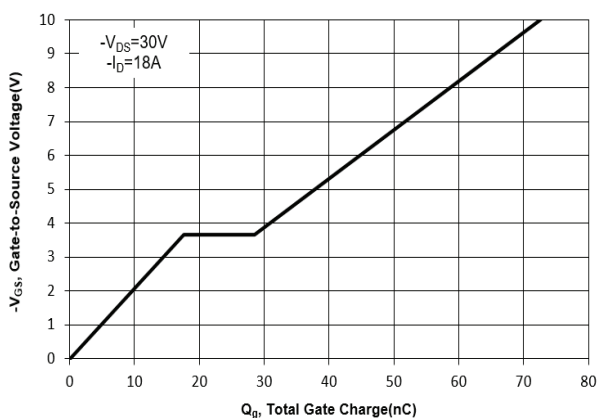
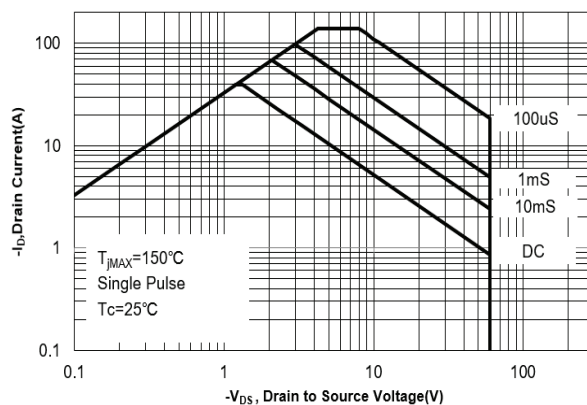


Fig. 12 Safe Operation Area



Electrical Characteristics Curves

Fig. 13 Normalized Maximum Transient Thermal Impedance($z_{\theta JC}$)

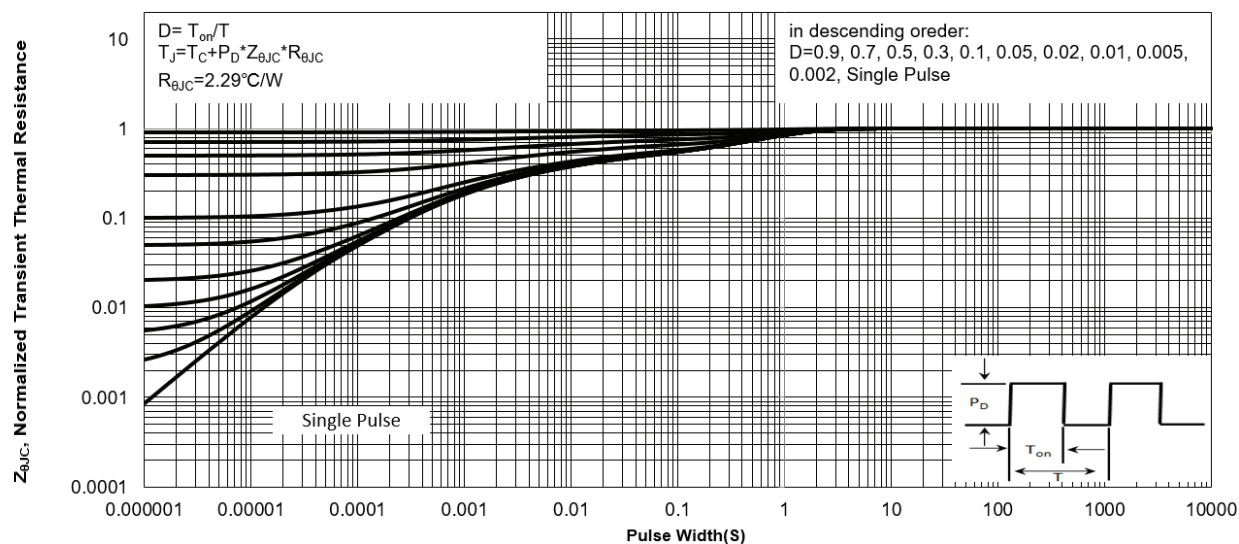
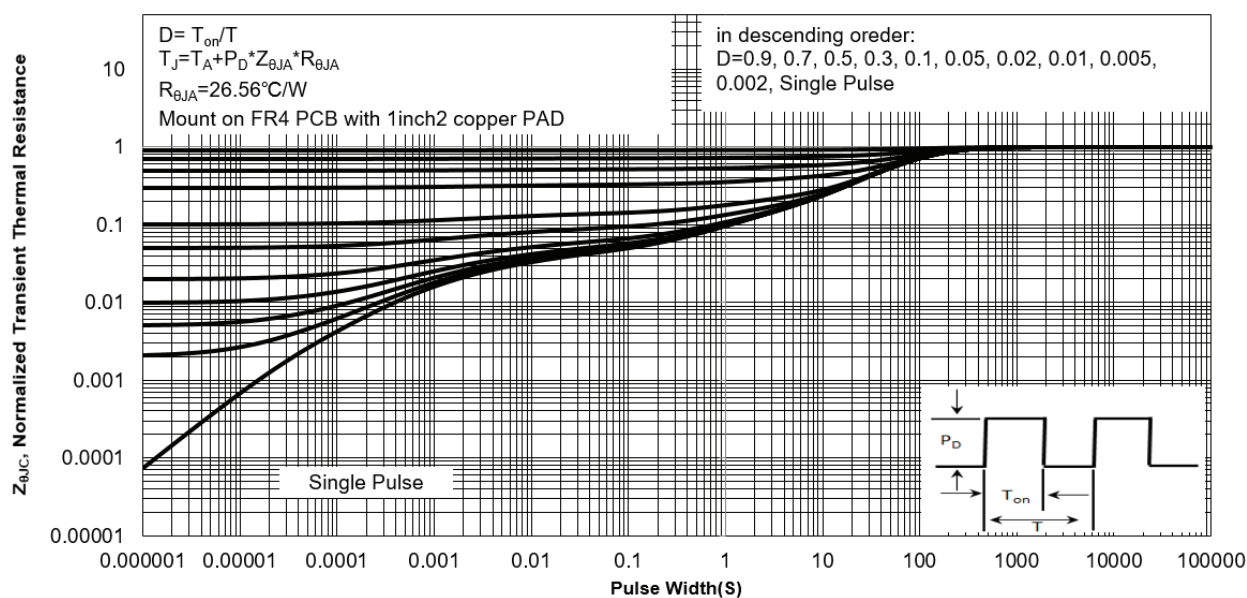
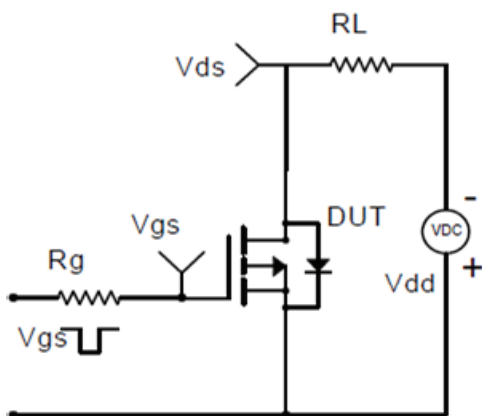
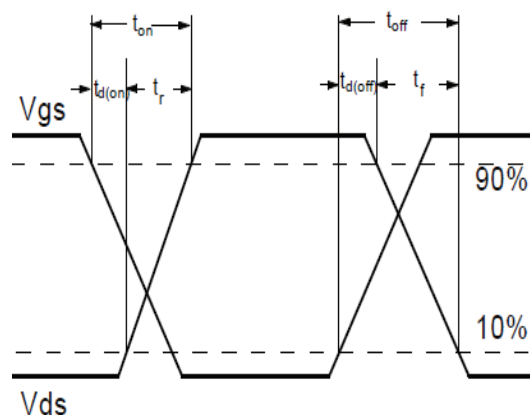
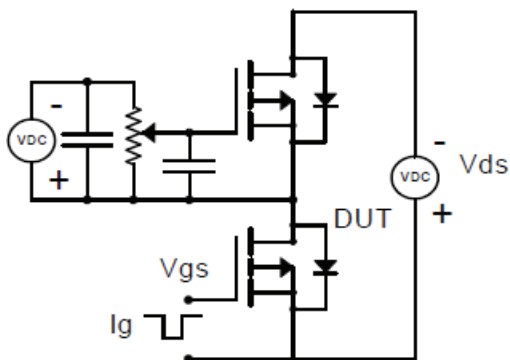
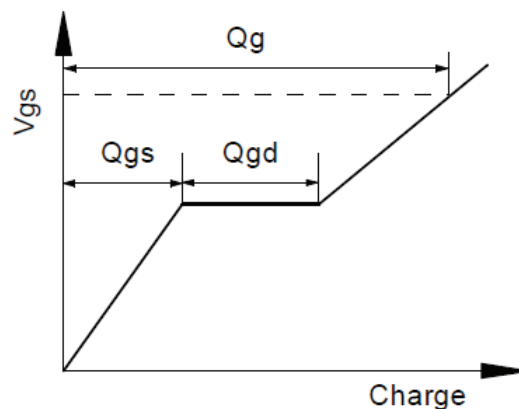
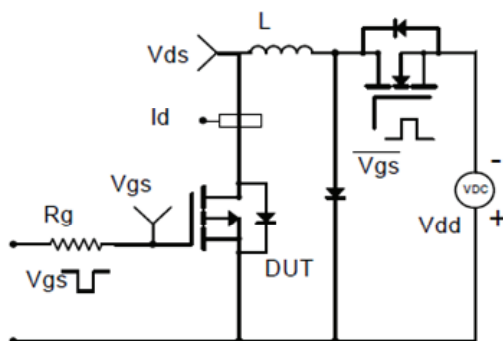
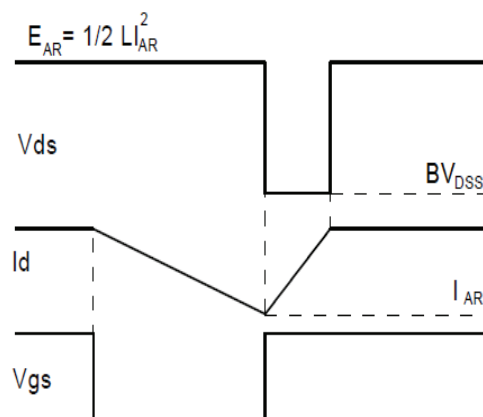


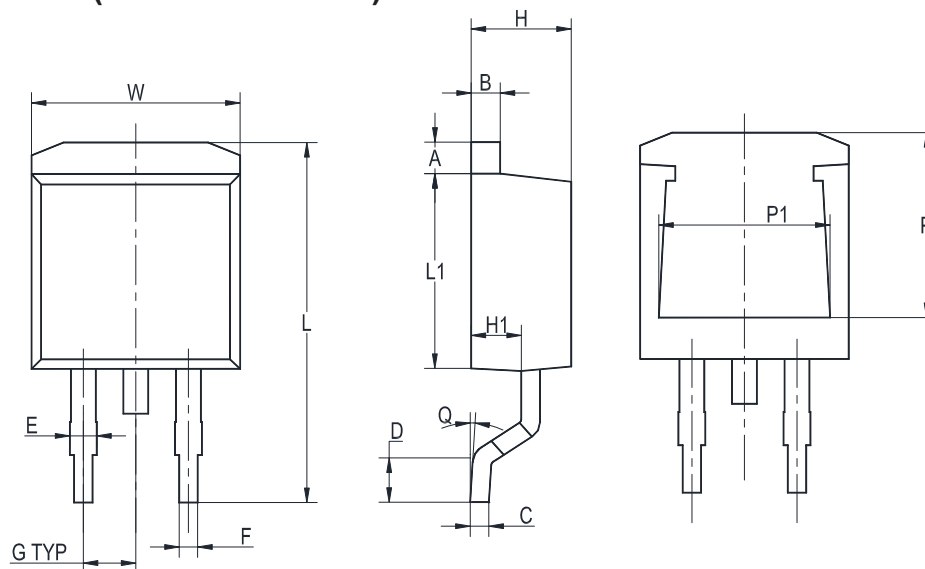
Fig. 14 Normalized Maximum Transient Thermal Impedance($z_{\theta JA}$)



Test Circuits
Fig.1-1 Switching times test circuit

Fig.1-2 Switching Waveform

Fig.2-1 Gate charge test circuit

Fig.2-2 Gate charge waveform

Fig.3-1 Avalanche test circuit

Fig.3-2 Avalanche waveform


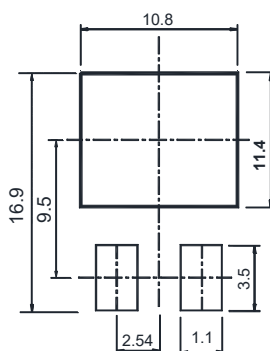
Package Outline (Dimensions in mm)

TO-263



UNIT	A	B	C	D	E	F	G	W	H	H1	L	L1	Q	P	P1
mm	1.5	1.5	0.5	2.60	1.6	0.94	2.54	10.5	4.8	2.9	16.5	8.7	8°	7.6	8.2
	1.1	1.1	0.3	2.15	1.1	0.68	TYP	9.6	4.4	2.5	14.5	8.2	MAX	7.1	7.4

Recommended Soldering Footprint



Packing information

Package	Reel Quantity	Box Quantity	Carton Quantity	Delivery Mode
TO-263	0.8 K / Reel	0.8 K / Box	4K pcs / Carton	Reel

Marking information

" TV06P240L " = Part No.

" ***** " = Date Code Marking

Font type: Arial



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